

# **iMAPS New England - 52nd Symposium & Expo**



**May 5, 2026**



**The Leading Regional Symposium Dedicated to  
Microelectronics, Assembly and Packaging**

## **CALL FOR ABSTRACTS**

**The Symposium Technical Committee is soliciting  
Abstracts for Lecture & Interactive Poster Presentations  
on all aspects of Microelectronics Assembly & Packaging  
Special Focus on Advanced Materials, Advanced Packaging,  
Additive Technology, Photonics & Microfabrication  
Student Submissions are Encouraged**



**Submit a 100-200 word abstract in WORD or PDF Format to: [Abstracts 52](#)**

**Include your contact information and whether you are a student**

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**Submission Deadline is December 15, 2025**



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